

ON Semiconductor®

## FDA20N50-F109

# N-Channel UniFET<sup>TM</sup> MOSFET 500 V, 20 A, 230 m $\Omega$

#### **Features**

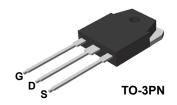
- $R_{DS(on)}$  = 230 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 10 A
- Low Gate Charge (Typ. 45.6 nC)
- Low C<sub>rss</sub> (Typ. 27 pF)
- · 100% Avalanche Tested
- · Improved dv/dt Capability

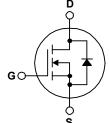
### **Applications**

- PDP TV
- · Uninterruptible Power Supply
- AC-DC Power Supply

# **Description**

UniFET<sup>TM</sup> MOSFET is ON Semiconductor's high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol	Parameter		FDA20N50-F109	Unit		
V <sub>DSS</sub>	Drain-Source Voltage			500	V	
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25°C) - Continuous (T <sub>C</sub> = 100°C)		22 13.2	A A	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	88	A	
V <sub>GSS</sub>	Gate-Source voltage			± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy		(Note 2)	1110	mJ	
I <sub>AR</sub>	Avalanche Current		(Note 1)	22	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy		(Note 1)	28.0	mJ	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	20	V/ns	
$P_{D}$	Power Dissipation	(T <sub>C</sub> = 25°C) - Derate above 25°C		280 2.3	W W/°C	
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C		
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C		

#### **Thermal Characteristics**

Symbol	Parameter	FDA20N50-F109	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.44	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	°C/W	

# **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
FDA20N50	FDA20N50-F109	TO-3PN	Tube	N/A	30 units

# **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
Off Characteristics							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 250\mu A$ , $T_J = 25^{\circ}C$	500			V	
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C		0.50		V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 400V, T <sub>C</sub> = 125°C			1 10	μ <b>Α</b> μ <b>Α</b>	
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V			100	nA	
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V			-100	nA	
On Charac	teristics			•	•		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 11A		0.20	0.23	Ω	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 11A		24.6		S	
Dynamic C	: Characteristics						
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 25V, $V_{GS}$ = 0V,		2400	3120	pF	
C <sub>oss</sub>	Output Capacitance	f = 1.0MHz		355	465	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			27		pF	
Switching	Characteristics			_			
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 250V, I <sub>D</sub> = 20A	-	95	200	ns	
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25\Omega$	ı	375	760	ns	
t <sub>d(off)</sub>	Turn-Off Delay Time			100	210	ns	
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)		105	220	ns	
$Q_g$	Total Gate Charge	V <sub>DS</sub> = 400V, I <sub>D</sub> = 20A	-	45.6	59.5	nC	
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10V		14.8		nC	
$Q_{gd}$	Gate-Drain Charge	(Note 4)		21.6		nC	
Drain-Sour	rce Diode Characteristics and Maximun	n Ratings		•	•		
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				20	Α	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				80	Α	
$V_{SD}$	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 22A			1.4	V	
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A		507		ns	
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt =100A/μs		7.20		μС	

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 4.1mH, I $_{AS}$  = 22A, V $_{DD}$  = 50V, R $_{G}$  = 25 $\Omega$ , Starting T $_{J}$  = 25 $^{\circ}$ C
- 3. I  $_{SD}$   $\leq$  22A, di/dt  $\leq$  200A/ $\mu$ s, V  $_{DD}$   $\leq$  BV  $_{DSS}$ , Starting T  $_{J}$  = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics

# **Typical Characteristics**

Figure 1. On-Region Characteristics

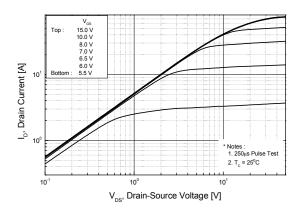


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

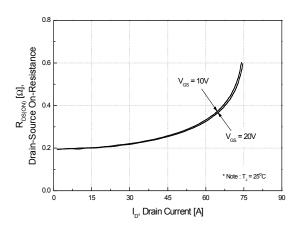


Figure 5. Capacitance Characteristics

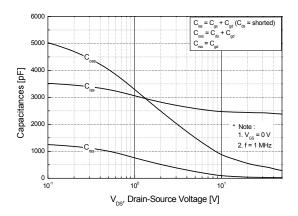


Figure 2. Transfer Characteristics

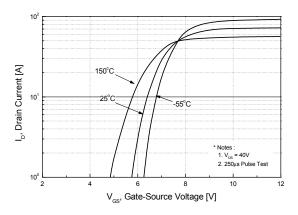


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

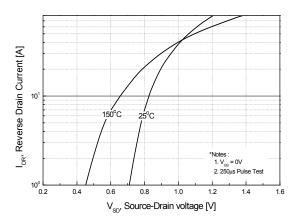
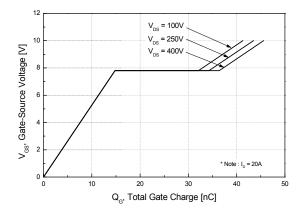


Figure 6. Gate Charge Characteristics



# Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

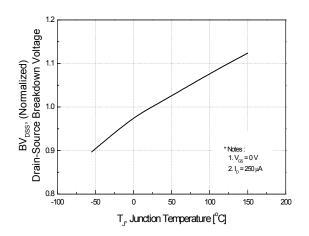


Figure 8. On-Resistance Variation vs. Temperature

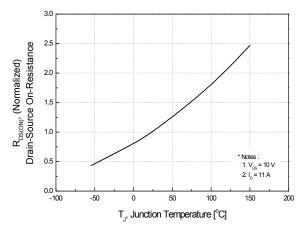
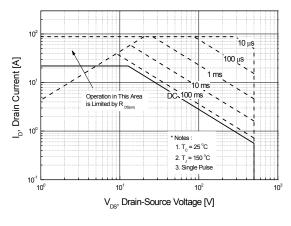


Figure 9. Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature



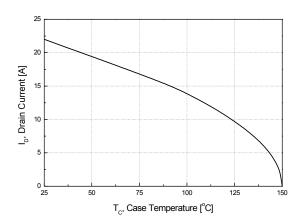


Figure 11. Transient Thermal Response Curve

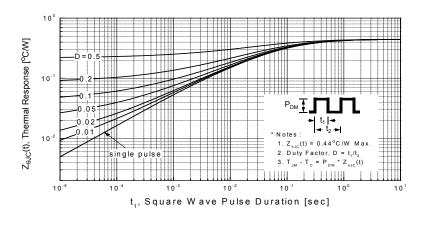


Figure 12. Gate Charge Test Circuit & Waveform

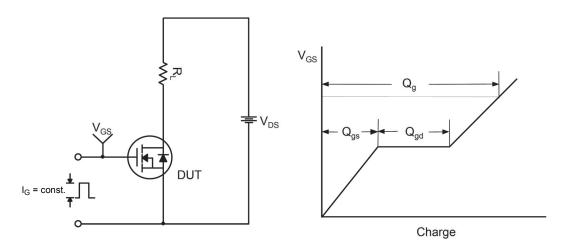


Figure 13. Resistive Switching Test Circuit & Waveforms

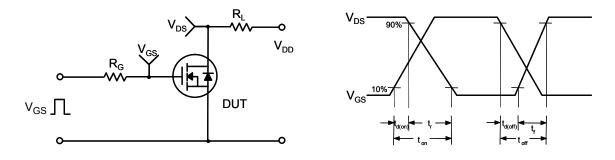
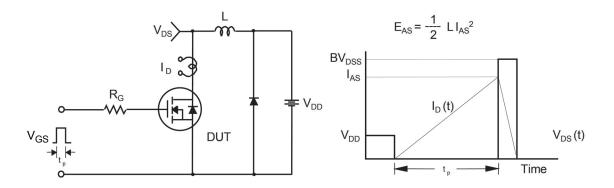


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



DUT

VDS

VDS

Driver

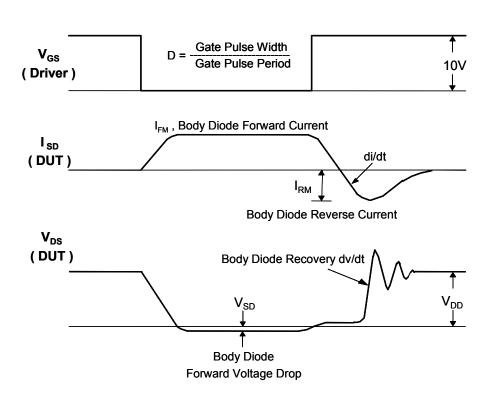
Same Type as DUT

VDD

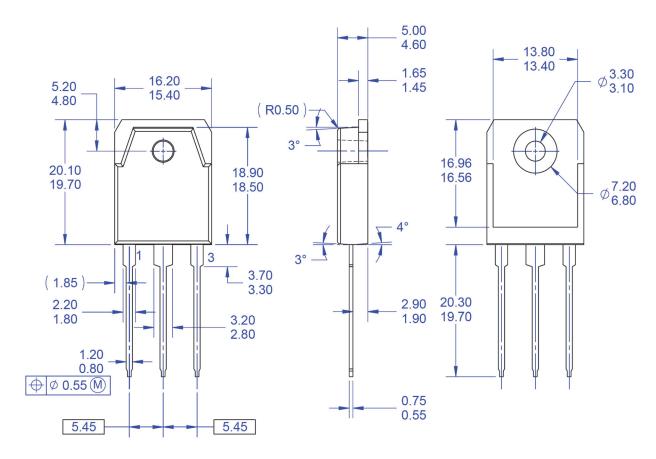
VDD

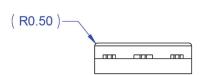
• dv/dt controlled by R<sub>G</sub>
• I<sub>SD</sub> controlled by pulse period

Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



#### **Mechanical Dimensions**





- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- **DIMENSION AND TOLERANCING PER** ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSSIONS.
  E) DRAWING FILE NAME: TO3PN03AREV1.
- F) FAIRCHILD SEMICONDUCTOR.

Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

Package drawings are provided as a service to customers considering ON Semiconductor components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a ON Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of ON Semiconductor's worldwide terms and conditions, specifically the warranty therein, which covers ON Semiconductor products.

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910

Phone: 421 33 790 2910 **Japan Customer Focus Center**Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative